

### Amendments to the Specification

Please amend paragraphs [0013], [0014], and [0019] through [0021] as follows:

**[0013]** Interface enhancing apparatus 10 may include a first component which may be a substantially horizontal component 18 extending from interface panel 12. Horizontal component 18 may include a flex circuit or other power and signal routing form factor such as a printed circuit board (PCB) or other carrier substrate. Horizontal component 18 may be removably coupled to interface panel 12 through an electrical communication interface such as a card edge connector or any other suitable connector, which may include, but are not limited to, various styles of pin and socket type connectors. In addition to wired connections, there could also be some variation of unwired connections, such as infrared, acoustic, light, or RF.

**[0014]** A second component, which may be a vertical component 20 may be coupled to horizontal component 18, and extend in a generally parallel manner to the interface panel 12. Vertical component 20 may include a carrier substrate or other power and signal routing device that is in electrical communication with the flex circuit of horizontal component 18. Vertical component 20 may have a plurality of enhanced interfaces 22 that are in electrical communication with the modular platform board 14 and the electronic components disposed thereon via the carrier substrate and flex circuit of vertical component 20 and horizontal component 18, respectively. Enhanced interfaces may include I/O interfaces similar to those suitable for mounting on the interface panel 12, and include, but are not limited to, USB, IEEE 1394, serial, ethernet, sonnet, and other interface ports. A variety of passive interfaces 26 may also be included on the opposite or outward facing edge 24 of vertical component 20, such that such passive interfaces 26 may be observed from a position facing the modular platform board 14.

**[0019]** It can be appreciated that the enhanced interfaces need not be positioned on the inward facing edge of vertical component 20, but may be positioned about the outward facing edge. **FIG. 3** illustrates a perspective view of an interface enhancing

apparatus in accordance with an embodiment of the present invention. A first component, for example a horizontal ~~Horizontal~~ component 140 40 may be removably coupled to interface panel 142 42 of modular platform board 141 41, and configured with a flex circuit or other routing device that may be in electrical communication with electronic components on the modular platform board 141 41.

**[0020]** A first component, for example a vertical ~~Vertical~~ component 144 46 may be mechanically and electrically coupled with horizontal component 140 40. A plurality of I/O interfaces 148 48 and passive interfaces 150 50 may be disposed on the outward facing edge 146 46 of vertical component 144 ~~component 44~~. The aggregate protrusion of interior cables 156 56, horizontal component 140 40, vertical component 144 ~~component 44~~ and outer cables 154 54 may be less than or equal to the allowable aggregate protrusion distance 152 52. Additional support brackets 158 58 may be used to structurally support vertical component 144 ~~component 44~~.

**[0021]** In one embodiment, a horizontal component may be configured to interface with an expansion slot 155 55 in the interface panel 142 42. An example of such an interconnection may be through a mezzanine card slot in ATCA modular platform boards.